

Low-Power µP Supervisor Circuits

FEATURES

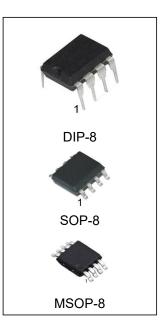
Improved replacements for the Maximum HGM1232/T/S/R

140µA maximum supply current

60% improvement

- Precision power supply monitor
 - 4.4V threshold (HGM1232)
 - 3.08V threshold (HGM1232T)
 - 2.93V threshold (HGM1232S)
 - 2.63V threshold(HGM1232R)
- Debounced manual reset input
- Voltage monitor
 - 1.25V threshold
 - Battery monitor/Auxiliary supply monitor
- Watchdog timer (HGM1232/ HGM1232T/HGM1232S/HGM1232R)
- 300ms reset pulse width

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DEVICE	Package Type	MARKING	Packing	Packing Qty
HGM1232N	DIP-8	HGM1232	TUBE	2000pcs/box
HGM1232TN	DIP-8	HGM1232T	TUBE	2000pcs/box
HGM1232SN	DIP-8	HGM1232S	TUBE	2000pcs/box
HGM1232RN	DIP-8	HGM1232R	TUBE	2000pcs/box
HGM1232M/TR	SOP-8	M1232	REEL	2500pcs/reel
HGM1232TM/TR	SOP-8	M1232T	REEL	2500pcs/reel
HGM1232SM/TR	SOP-8	M1232S	REEL	2500pcs/reel
HGM1232RM/TR	SOP-8	M1232R	REEL	2500pcs/reel
HGM1232MM/TR	MSOP-8	M1232	REEL	3000pcs/reel
HGM1232TMM/TR	MSOP-8	M1232T	REEL	3000pcs/reel
HGM1232SMM/TR	MSOP-8	M1232S	REEL	3000pcs/reel
HGM1232RMM/TR	MSOP-8	M1232R	REEL	3000pcs/reel



DESCRIPTION

The HGM1232/HGM1232T/HGM1232S/HGM1232R CMOS supervisor circuits monitor power-supply and battery voltage level, and µP/µC operation. Compared to pin-compatible devices offered by Maxim Integrated Products, these devices feature 60 percent lower maximum supply current.

The family offers several functional options. Each device generates a reset signal during power-up, power-down and during brownout conditions.

A reset is generated when the supply drops below4.4V(HGM1232),3.08V (HGM1232T),2.93V (HGM1232S), 2.63V(HGM1232R). In addition,the HGM1232/T/S/R feature a 2.4 second watchdog timer. A versatile power-fail circuit has a 1.25V threshold, useful in checking battery levels and non-5V supplies. All devices have a manual reset (\overline{MR}) input. The watchdog timer output will trigger a reset if connected to \overline{MR} .

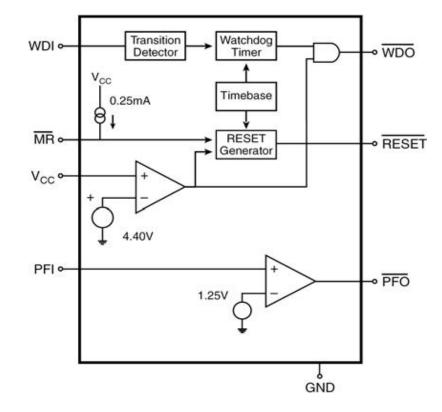
All devices are available in DIP8, SOP8 and MSOP8 packages.

APPLICATIONS

- Computers and embedded controllers
- Battery-operated systems
- Intelligent instruments

Wireless communication systems

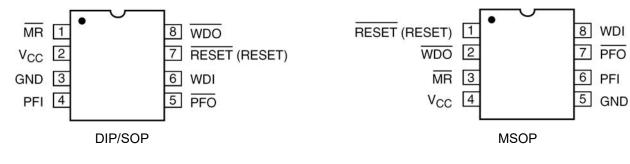
PDAs and handheld equipment



B L OCK DIAGRAM



PIN CONFIGURATION



PIN DESCRIPTION

Pin No.					
HGM123	32	Name	Pin Function		
DIP/SOP	MSOP				
1	3	MR	Manual RESET input. The activeLOW input triggers a reset pulse. A 250µA pull-up current allows the pin to be driven by TTL / CMOS logic or shortedto ground with a switch.		
2	4	Vcc	+5V power supply input.		
3	5	GND	Ground reference for all signals.		
4	6	PFI	Power-fail voltage monitor input. With PFI less than 1.25V, <i>PFO</i> goes low. Connect PFI to ground or VCC when not used.		
5	7	PFO	Power-fail output. The output is active LOW and sinks current when PFI is less than1.25V.		
6	8	WDI	Watchdog input. WDI controls the internal watchdog timer. AHIGH or LOW signal for2.4sec at WDI allows the internal timer to run-out, setting \overline{WDO} LOW. The watchdog function is disabled by floating WDI or by connecting WDI to a high-impedance		
6	8	WDI	three-state buffer. The internal watchdog timer clears when:RESET is asserted; WDI is three-stated; or WDI sees a rising or falling edge.		
7	1	RESET	Active-LOW reset output. Pulses LOW for 300ms when triggered, and stays low whenever Vcc is below the reset threshold (HGM1232:4.4V, HGM1232T: 3.08V, HGM1232S:1.93V,HGM1232R:2.63). <i>RESET</i> remains LOW for 300ms after Vcc rises above the RESET threshold or <i>MR</i> goes fromLOW to HIGH. A watchdog timeout will not trigger <i>RESET</i> unless <i>WDO</i> is connected to <i>MR</i> .		
8	2	WDO	Watchdog output. \overline{WDO} pullsLOW when the 2.4 sec internalwatchdog timer times-out anddoes not go HIGH until thewatchdog is cleared. In addition, when Vcc is below the reset threshold, \overline{WDO} remains low. Unlike \overline{RESET} , \overline{WDO} does not have a minimum pulse width andas soon as Vcc exceeds the reset threshold, \overline{WDO} goes HIGH withno delay.		



ABSOLUTE MAXIMUM RATING $(Ta=25^{\circ}C)^1$

Characteristics	Value	Unit
Supply voltage	-0.3~+6.0	V
All other inputs *2	-0.3~Vcc+0.3	V
Input current at Vcc and GND	20	mA
Output current :All outputs	20	mA
Rate of Rise at Vcc	100	V/µs
Plastic DIP power dissipation (Derate 9mW/ $^{\circ}$ above 70 $^{\circ}$)	700	mW
SOP power dissipation (Derate 5.9mW/ $^\circ C$ above 70 $^\circ C$)	470	mW
MSOP power dissipation (Derate 4.1mW/ $^{\circ}$ C above 70 $^{\circ}$ C)	330	mW
Operating temperature range	0~70	°C
Storage temperature range	-65~+150	°C
Lead temperature (soldering,10 sec.)	245	°C

Note:1、 Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not ensured. *2、 The input voltage limits on PFI and MR can be exceeded if the input current is less than10mA.



ELECTRICAL CHARACTERISTICS

(Unless otherwise noted, V_{CC} = 4.5V to 5.5V for the HGM1232/HGM1232T/HGM1232S/HGM1232R)

Characteristics	Symbol	Conditions	Min.	Тур.	Max	Unit	
Operating voltage range	Vcc	HGM1232/T/S/R	1.2		5.5	V	
Supply current	lcc	HGM1232/T/S/R		75	140	μA	
		HGM1232	4.25	4.4	4.4 4.5		
RESET threshold		HGM1232T	2.98	3.08	3.15	v	
	V RT	HGM1232S	2.83	2.93	3	V	
		HGM1232R	2.54	2.63	2.69		
RESET threshold hysteresis				40		mV	
RESET pulse width	tRS		140	300	420	ms	
\overline{MR} pulse width	^t MR		0.15			μs	
\overline{MR} to \overline{RESET} outdelay	t MD				0.25	μs	
	VIH		2.0				
MR input threshold	VIL				0.8	V	
MR pull-up current		<u>₩</u> R=0V	100	250	600	μA	
		ISOURCE =800µA	Vcc-1.5				
<u>RESET</u> output voltage		ISINK =3.2mA			0.4	v	
niisii output vonago		HGM1232/T/S/R,Vcc=1.2			0.3	·	
		V, ISINK =100µA					
Watchdog timeout period	tWD	HGM1232/T/S/R	2.00	2.4	3.00	S	
WDI pulse width	tWP	VIL =0.4V,VIH =0.8Vcc	50			ns	
WDI input threshold	V IH	HGM1232/T/S/R,Vcc=5V	3.5			V	
	V IL	· · · · · · · · · · · · · · · · · · ·			0.8	v	
WDI input current		HGM1232 /T/S/R,WDI=Vcc		50	150	μA	
		HGM1232/T/S/R,WDI=0V	-150	-50		μΛ	
		HGM1232/T/S/R,	Vcc-1.5				
WDO output voltage		ISOURCE =800µA	100 1.0			v	
		HGM1232/T/S/R,			0.4	v	
		ISINK =1.2mA			0.4		
PFI input threshold		Vcc=5V	1.20	1.25	1.30	V	
PFI input current			-25	0.01	25	nA	
<u><i>PFO</i></u> output voltage		ISOURCE =800µA	Vcc-1.5			V	
rro output voltage		ISINK =3.2mA			0.4	v	

FEATURE SUMMARY

	HGM1232	HGM1232T	HGM1232S	HGM1232R
Power-fail detector	•	•	•	•
Brownout detection	•	•	•	•
Manual RESET input	•	•	•	•
Power-up/down RESET	•	•	•	•
Watchdog timer	•	•	•	•
Active-HIGH RESET output				
Active-LOW RESET output	•	•	•	•
RESET threshold	4.4V	3.08V	2.93V	2.63V



DETAIL DESCRIPTIONS

RESET Operation

The \overline{RESET} signals are designed to start a $\mu P/\mu C$ in a known state or return the system to a known state.

 \overline{RESET} is guaranteed to be LOW with Vcc above 1.2V. During a power-up sequence, \overline{RESET} remains low until the supply rises above the threshold level, either 4.4V, 3.08V, 2.93V or 2.63V. \overline{RESET} goes high approximately 300ms after crossing the threshold.

During power-down, \overline{RESET} goes LOW as Vcc falls below the threshold level and is guaranteed to be under 0.4V with Vcc above 1.2V. In a brownout situation where Vcc falls below the threshold level, \overline{RESET} pulses low.

If a brownout occurs during an already initiated reset, the pulse will continue for a minimum of 140ms.

Auxiliary Comparator

All devices have an auxiliary comparator with 1.25V trip point and uncommitted output (\overline{PFO}) and noninverting input (PFI). This comparator can be used as a supply voltage monitor with an external resistor voltage divider. The attenuated voltage at PFI should be set just below the 1.25 threshold. As the supply level falls, PFI is reduced causing the \overline{PFO} output to transit LOW. Normally PFO interrupts the processor so the system can be shut down in a controlled manner.

Manual Reset (\overline{MR})

The active-LOW manual reset input is pulled high by a 250µA pull-up current and can be driven low by CMOS/TTL logic or a mechanical switch to ground. An external debounce circuit is unnecessary since the 140ms minimum reset time will debounce mechanical pushbutton switches.

By connecting the watchdog output (WDO) and MR, a watchdog timeout forces RESET to be generated.

Watchdog Timer

The watchdog timer available on the HGM1232/HGM1232T/HGM1232S/HGM1232R monitors $\mu P/\mu C$ activity. If activity is not detected within 2.4 seconds, the internal timer puts the watchdog output, \overline{WDO} , into a LOW state. \overline{WDO} will remain LOW until activity is detected at WDI.

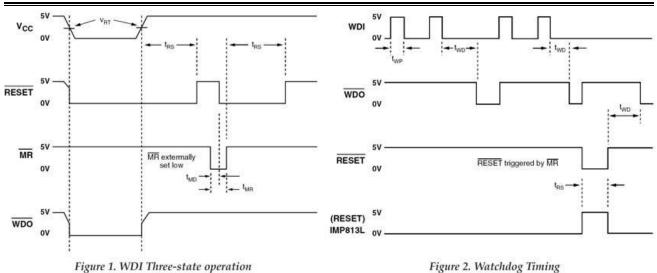
The watchdog function is disabled, meaning it is cleared and not counting, if WDI is floated or connected to a three-stated circuit. The watchdog timer is also disabled if RESET is asserted. When RESET becomes inactive and the WDI input sees a high or low transition as short as 50ns, the watchdog timer will begin a 2.4 second countdown.

Additional transitions at WDI will reset the watchdog timer and initiate a new countdown sequence.

 \overline{WDO} will also become LOW and remain so, whenever the supply voltage, Vcc , falls below the device threshold level. \overline{WDO} goes HIGH as soon as Vcc transitions above the threshold. There is no minimum pulse width for \overline{WDO} as there is for the RESET outputs. If WDI is floated, \overline{WDO} essentially acts as a low-power output indicator.



HGM1232



APPLICATION INFORMATION

Ensuring That \overline{RESET} is Valid Down to Vcc = 0V

When Vcc falls below 1.1V, the HGM1232/HGM1232T/HGM1232S/HGM1232R \overline{RESET} output no longer pulls down; it becomes indeterminate. To avoid the possibility that stray charges build up and force \overline{RESET} to the wrong state, a pull-down resistor should be connected to the \overline{RESET} pin,thus draining such charges to ground and holding RESET low. The resistor value is not critical. A 100k Ω resistor will pull \overline{RESET} to ground without loading it.

Bi-directional Reset Pin Interfacing

The HGM1232/HGM1232T/HGM1232S/HGM1232R can interface with $\mu P/\mu C$ bi-directional reset pins by connecting a 4.7k Ω resistor in series with the \overline{RESET} output and the $\mu P/\mu C$ bi-directional \overline{RESET} pin.

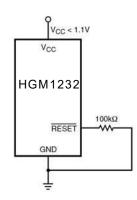


Figure 3. Ensuring That \overline{RESET} is Valid Down to $V_{CC} = 0V$

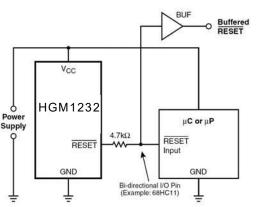


Figure 3. Bi-directional Reset Pin Interfacing



Monitoring Voltages Other Than Vcc

The HGM1232/HGM1232T/HGM1232S/HGM1232R can monitor voltages other than Vcc using the Power Fail circuitry. If a resistive divider is connected from the voltage to be monitored to the Power Fail input, PFI, the \overline{PFO} (output) will go LOW if the divider voltage goes below its 1.25V reference. Should hysteresis be desired, connect a resistor (equal to approximately 10 times the sum of the two resistors in the divider) between the PFI and \overline{PFO} pins. A capacitor between PFI and GND will reduce circuit sensitivity to input high-frequency noise. If it is desired to assert a RESET in addition to the \overline{PFO} flag, this may be achieved by connecting the \overline{PFO} output to \overline{MR} .

Monitoring a Negative Voltage

The Power-Fail circuitry can also monitor a negative supply rail. When the negative rail is OK, \overline{PFO} will be LOW, and when the negative rail is failing (not negative enough), \overline{PFO} goes HIGH(the opposite of when positive voltages are monitored). To trigger a reset, these outputs need to be inverted: adding the resistors and transistor as shown achieves this. The *RESET* output will then have the same sense as for positive voltages: good = HIGH, bad = LOW. It should be noted that this circuit's accuracy depends on the Vcc line, the PFI threshold tolerance, and the resistors.

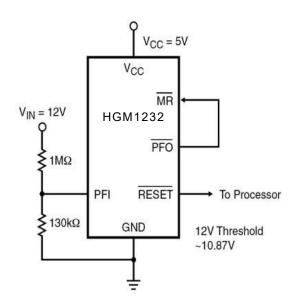


Figure 4. Monitoring Voltages Other Than Vcc

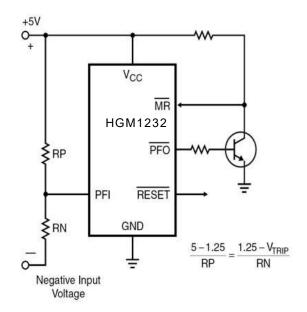
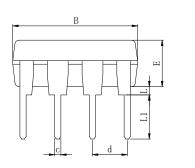


Figure 5. Monitoring a Negative Voltage



PHYSICAL DIMENSIONS

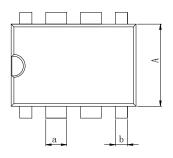
DIP-8





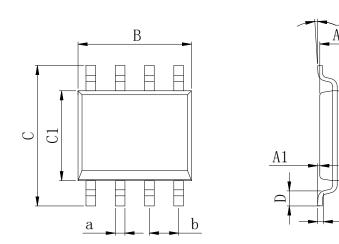
Q

0.25



Dimensions In Millimeters(DIP-8)											
Symbol:	A	В	D	D1	E	L	L1	а	b	с	d
Min:	6.10	9.00	8.10	7.42	3.10	0.50	3.00	1.50	0.85	0.40	2.54.000
Max:	6.68	9.50	10.9	7.82	3.55	0.70	3.60	1.55	0.90	0.50	2.54 BSC

SOP-8 (150mil)



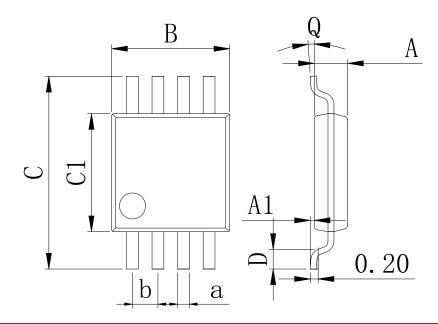
Dimensions In Millimeters(SOP-8)										
Symbol:	А	A1	В	С	C1	D	Q	а	b	
Min:	1.35	0.05	4.90	5.80	3.80	0.40	0°	0.35	1 07 000	
Max:	1.55	0.20	5.10	6.20	4.00	0.80	8°	0.45	1.27 BSC	

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PHYSICAL DIMENSIONS

MSOP-8



Dimensions In Millimeters(MSOP-8)									
Symbol:	А	A1	В	С	C1	D	Q	а	b
Min:	0.80	0.05	2.90	4.75	2.90	0.35	0°	0.25	0.65.890
Max:	0.90	0.20	3.10	5.05	3.10	0.75	8°	0.35	0.65 BSC



REVISION HISTORY

DATE	REVISION	PAGE
2017-1-5	New	1-12
2023-9-14	Update Lead Temperature、Updated DIP-8 dimension、 Add annotation for Maximum Ratings.	4、9



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